

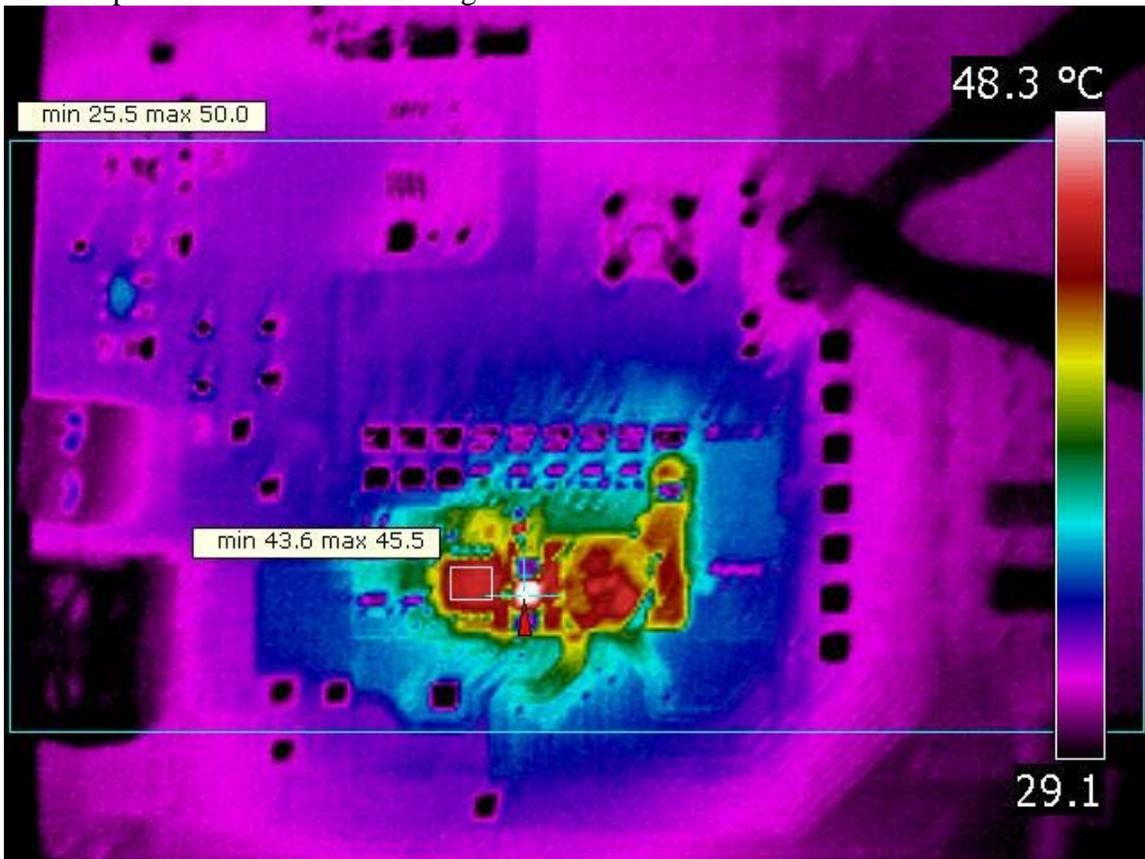
Table of Contents:

Page 1:	Thermal image 14 Vin full load model T1
Page 2:	Thermal image 19 Vin full load model T3
Page 3:	Main waveforms 14 Vin full load model T1
Page 4:	Main waveform 19 Vin full load models T2 & T3
Page 5:	output ripple 19 Vin full 5A load models T2 & T3
Page 6:	Step load and load dump response model T3

Note: Main switch Q1 CSD86330Q3D is actually rated to 25Vds, not 30Vds. Hence, operation off inputs above 15V is not recommended.

Thermal:

PMP5486: 14.14Vin 411mAin 0.965Vout 5.00A 500kHz  
snubber hot at 50; dual FET CSD86330Q3 at 45.5  
choke top at 46 ambient at 23-25 degrees C



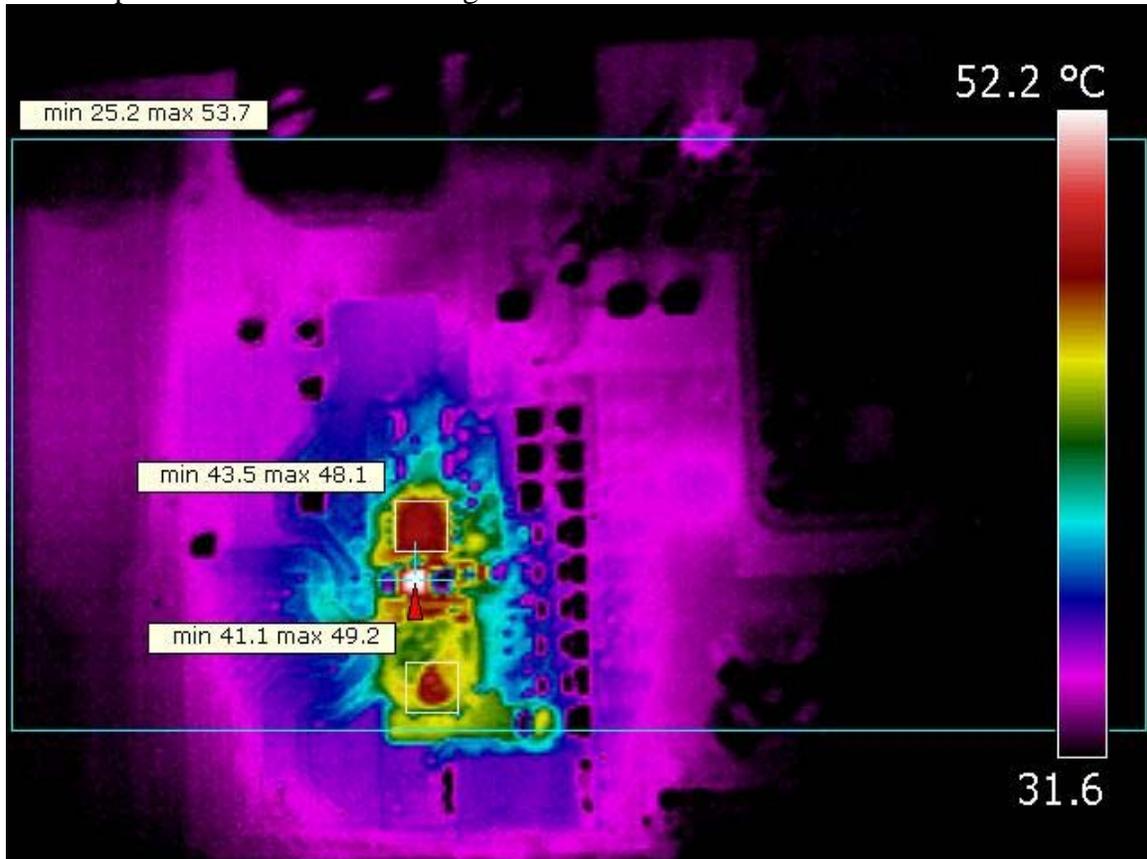
Qq  
Qq

19Vin thermal model T3:

PMP5486: 19Vin 315mAin 0.969Vout 5.00A 500kHz model t3

snubber hot at 54; dual FET CSD86330Q3 at 48

choke top at 49 ambient at 23-25 degrees C

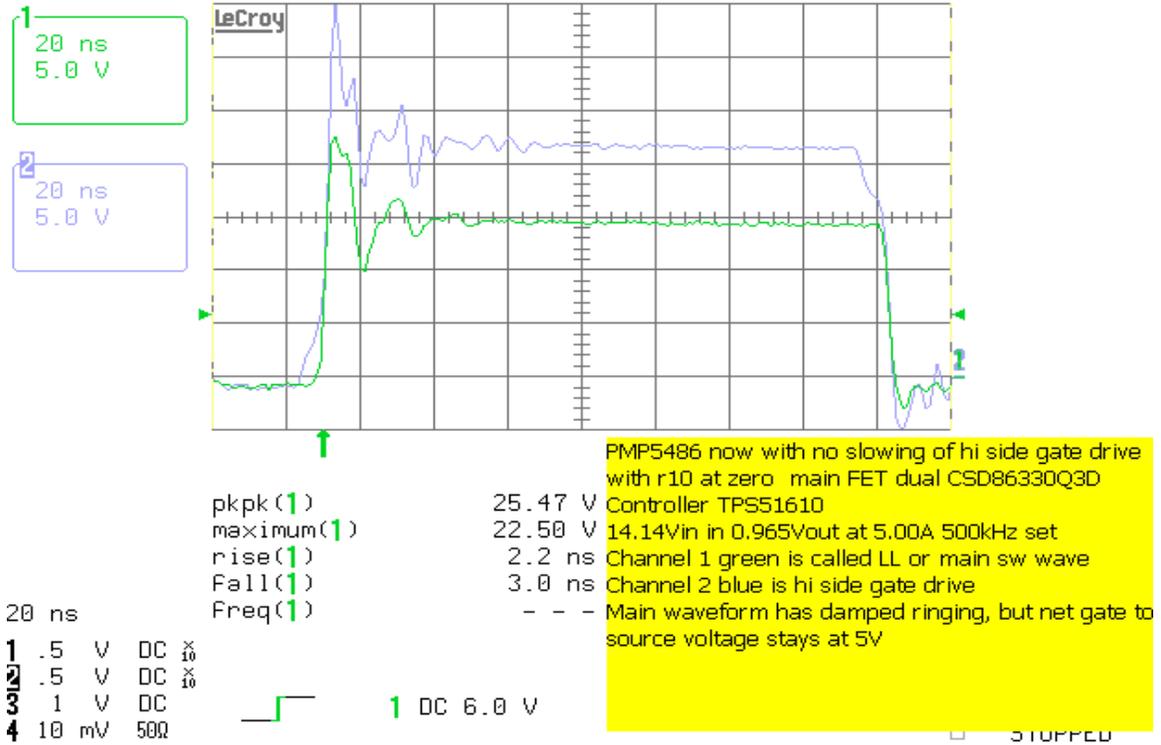


Qq

Note: Main switch Q1 CSD86330Q3D is actually rated to 25Vds, not 30Vds. Hence, operation off inputs above 15V is not recommended.

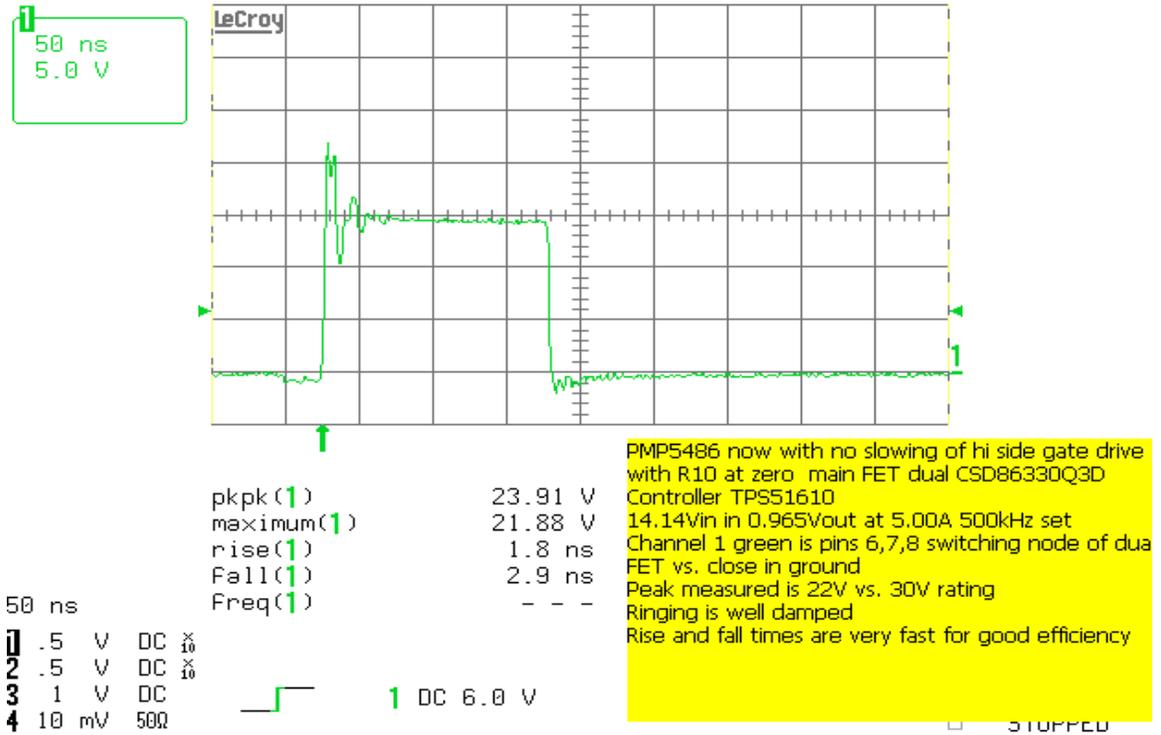
Main waveforms with 14Vin and 5A load: Model T1

17-Jun-10  
18:31:36



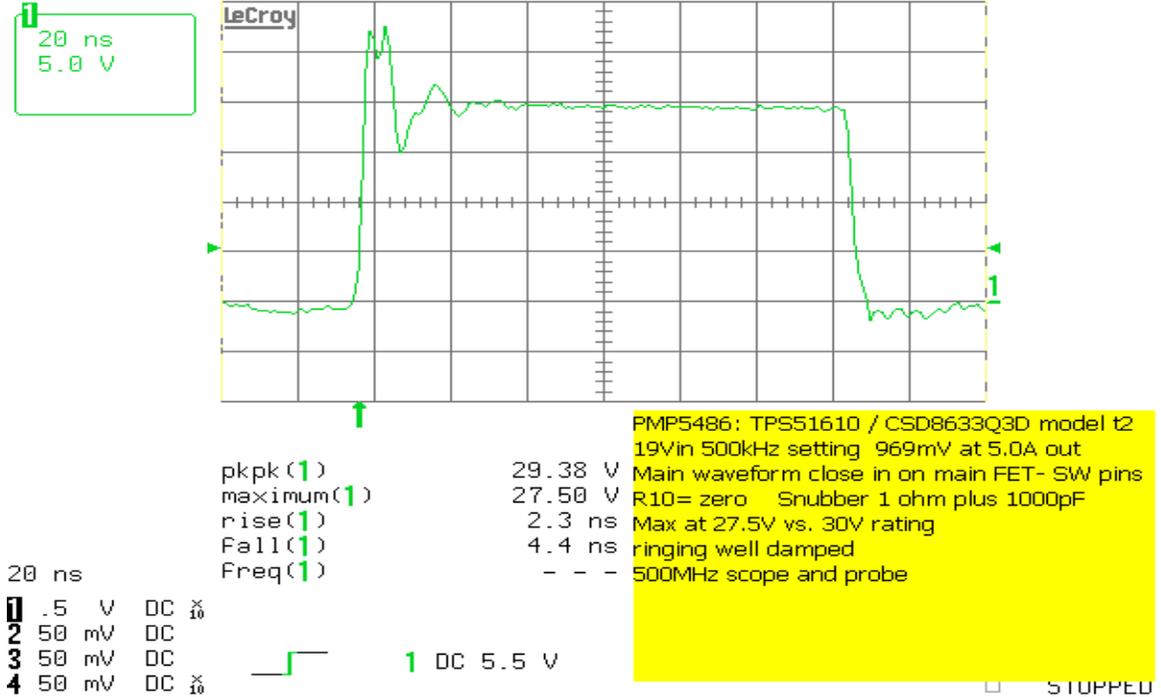
Now close in probe of just Vds of low side FET when hi side turns on:

17-Jun-10  
18:36:19



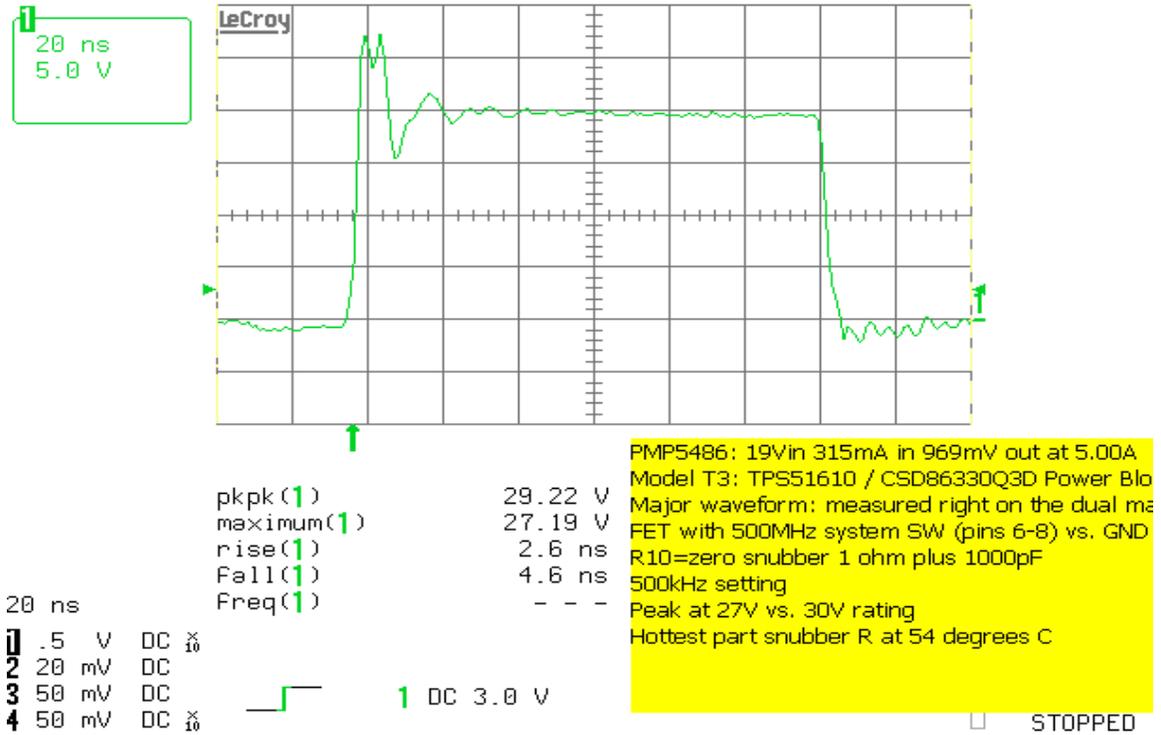
Main waveform: 19Vin model T2

21-Jun-10  
16:54:43



Same with model T3:

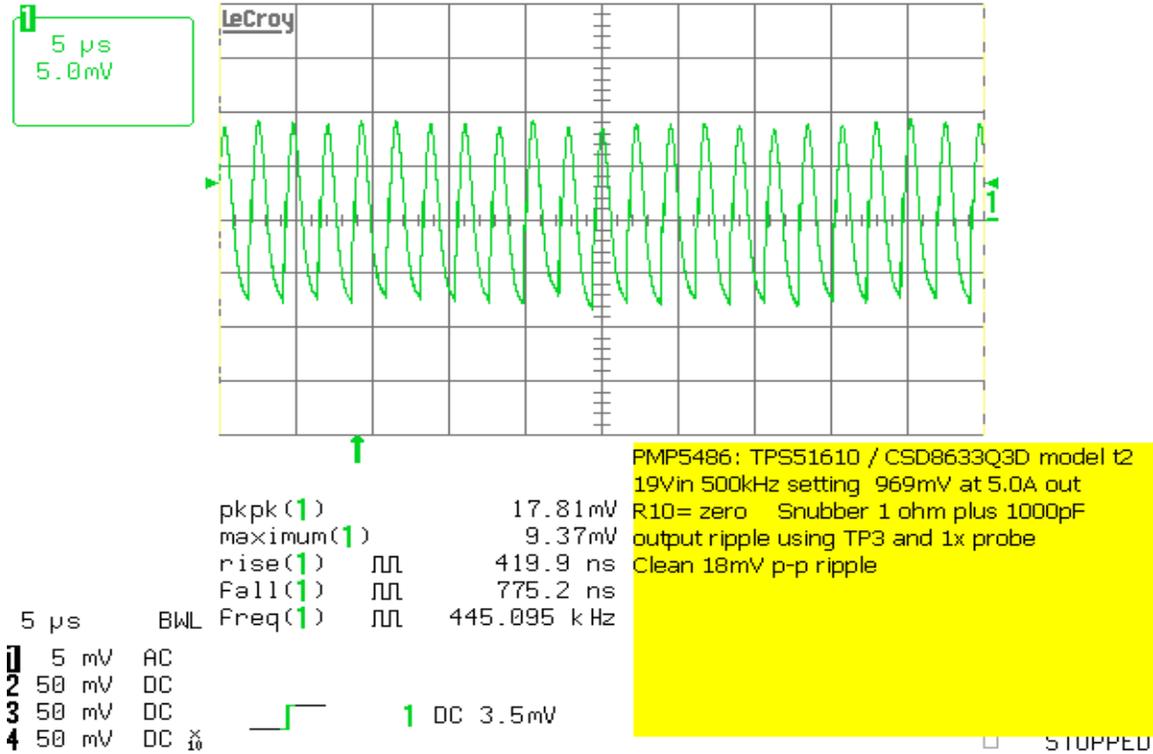
22-Jun-10 Reading Floppy Disk Drive  
14:39:43



Qq

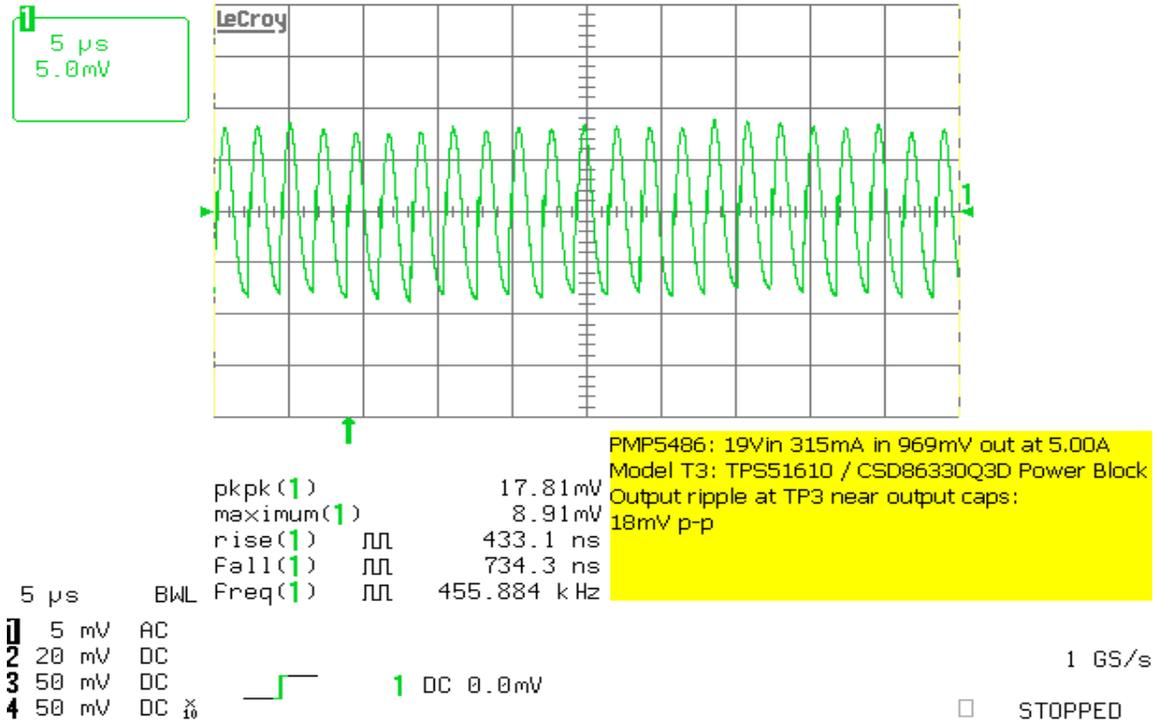
Output ripple: 19vin full load model T2

21-Jun-10  
17:02:14



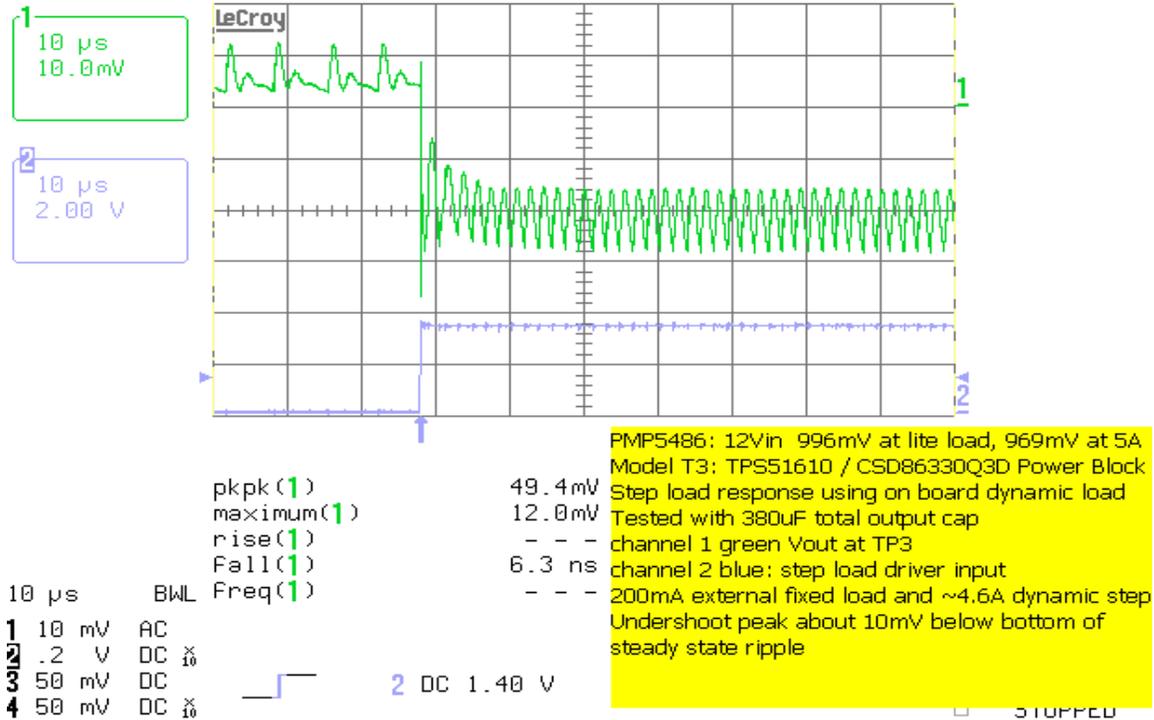
Same, but model T3:

22-Jun-10  
14:42:45



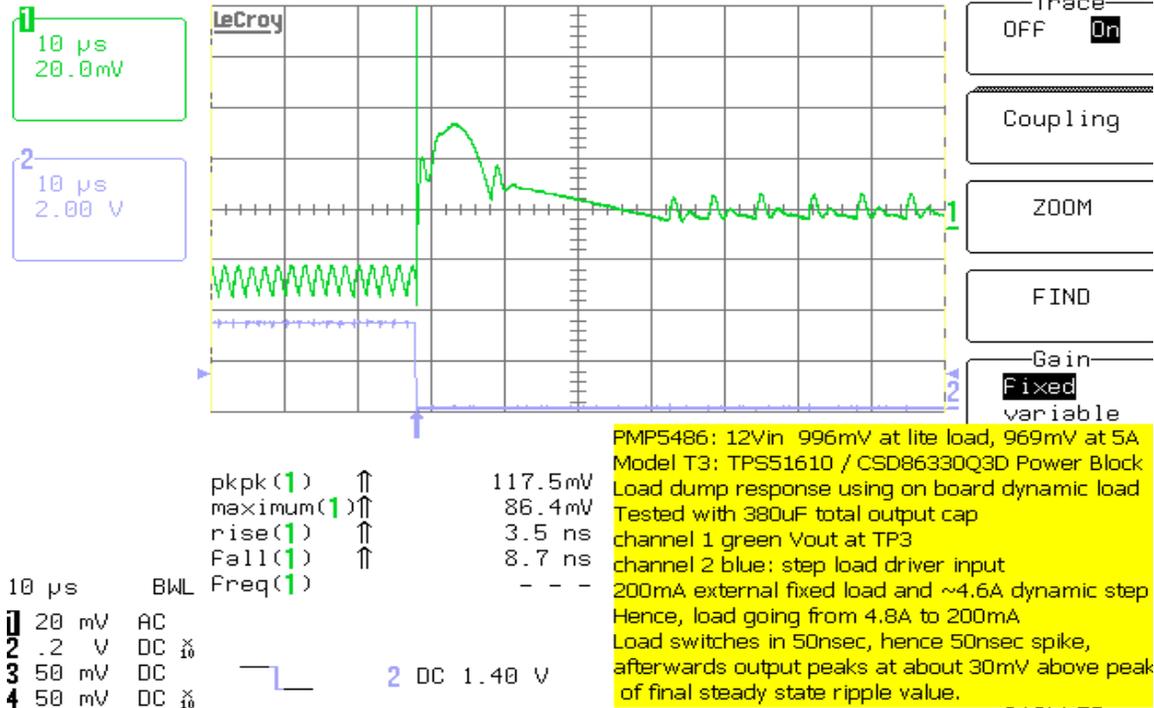
Load step response: model T3: 12Vin

22-Jun-10  
14:49:25



Load dump response: Model T3

22-Jun-10  
14:54:04



## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (<https://www.ti.com/legal/termsofsale.html>) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2021, Texas Instruments Incorporated